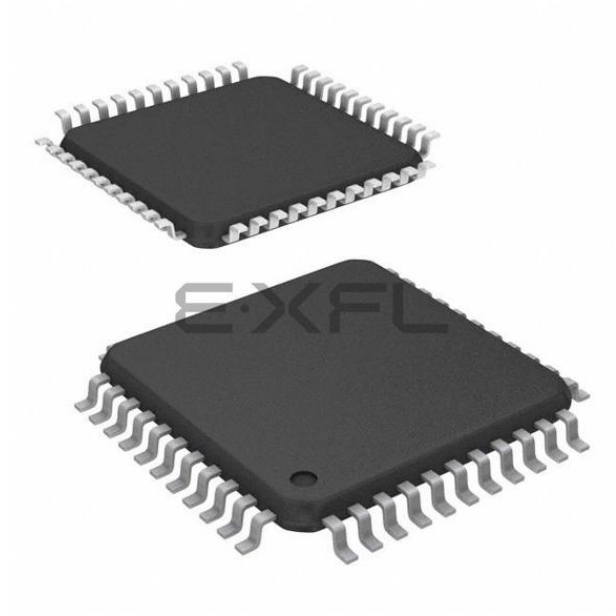
Infineon Technologies - CY37064VP44-100AXCT Datasheet



Welcome to E-XFL.COM

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In-System Reprogrammable™ (ISR™) CMOS
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	37
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy37064vp44-100axct

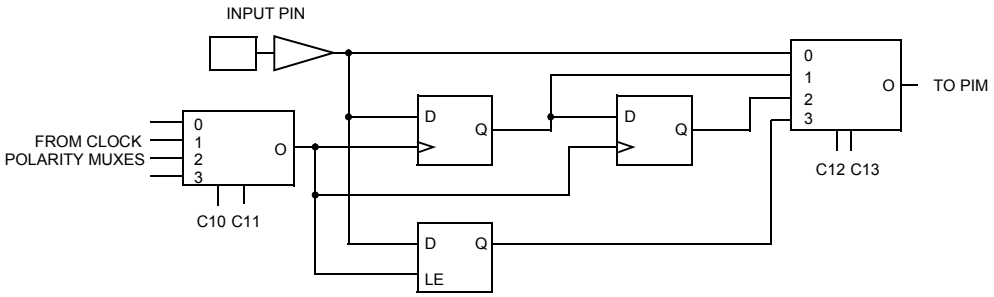


Figure 3. Input Macrocell

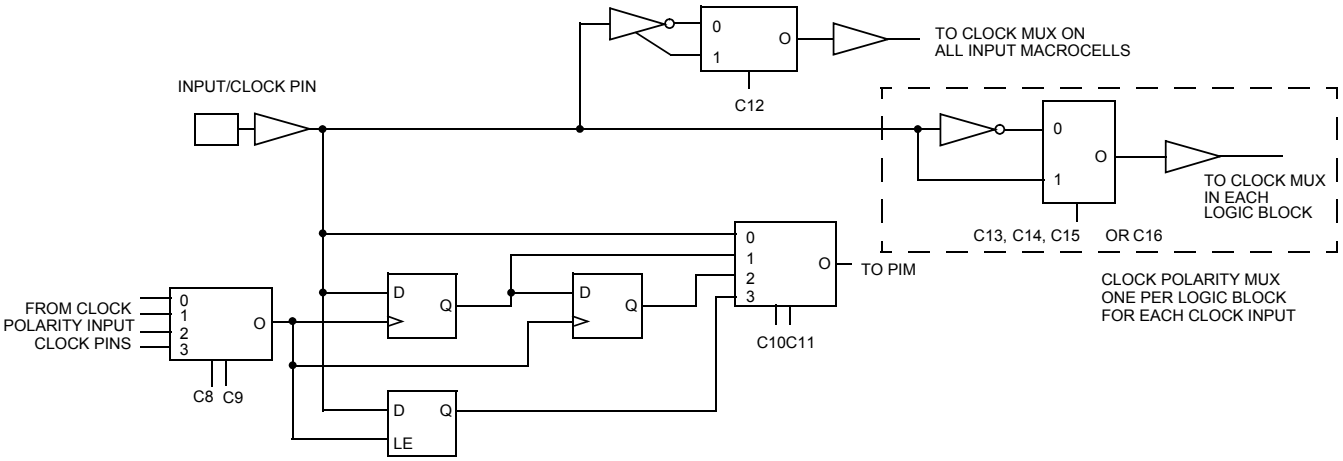


Figure 4. Input/Clock Macrocell

Clocking

Each I/O and buried macrocell has access to four synchronous clocks (CLK0, CLK1, CLK2 and CLK3) as well as an asynchronous product term clock PTCLK. Each input macrocell has access to all four synchronous clocks.

Dedicated Inputs/Clocks

Five pins on each member of the Ultra37000 family are designated as input-only. There are two types of dedicated inputs on Ultra37000 devices: input pins and input/clock pins. *Figure 3* illustrates the architecture for input pins. Four input options are available for the user: combinatorial, registered, double-registered, or latched. If a registered or latched option is selected, any one of the input clocks can be selected for control.

Figure 4 illustrates the architecture for the input/clock pins. Like the input pins, input/clock pins can be combinatorial, registered, double-registered, or latched. In addition, these pins feed the clocking structures throughout the device. The clock path at the input has user-configurable polarity.

Product Term Clocking

In addition to the four synchronous clocks, the Ultra37000 family also has a product term clock for asynchronous clocking. Each logic block has an independent product term clock which is available to all 16 macrocells. Each product term clock also supports user configurable polarity selection.

Timing Model

One of the most important features of the Ultra37000 family is the simplicity of its timing. All delays are worst case and system performance is unaffected by the features used. *Figure 5* illustrates the true timing model for the 167-MHz devices in high speed mode. For combinatorial paths, any input to any output incurs a 6.5-ns worst-case delay regardless of the amount of logic used. For synchronous systems, the input set-up time to the output macrocells for any input is 3.5 ns and the clock to output time is also 4.0 ns. These measurements are for any output and synchronous clock, regardless of the logic used.

The Ultra37000 features:

- No fanout delays
- No expander delays
- No dedicated vs. I/O pin delays
- No additional delay through PIM
- No penalty for using 0–16 product terms
- No added delay for steering product terms
- No added delay for sharing product terms
- No routing delays
- No output bypass delays

The simple timing model of the Ultra37000 family eliminates unexpected performance penalties.

The third programming option for Ultra37000 devices is to utilize the embedded controller or processor that already exists in the system. The Ultra37000 ISR software assists in this method by converting the device JEDEC maps into the ISR serial stream that contains the ISR instruction information and the addresses and data of locations to be programmed. The embedded controller then simply directs this ISR stream to the chain of Ultra37000 devices to complete the desired reconfiguring or diagnostic operations. Contact your local sales office for information on availability of this option.

The fourth method for programming Ultra37000 devices is to use the same programmer that is currently being used to program FLASH370i devices.

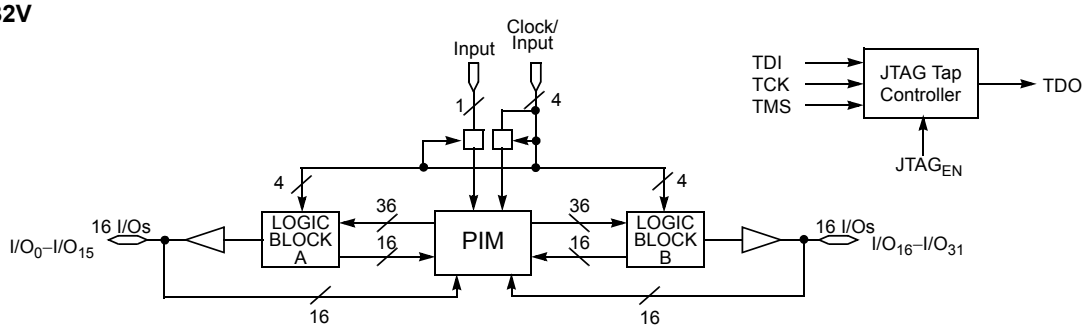
For all pinout, electrical, and timing requirements, refer to device data sheets. For ISR cable and software specifications, refer to the UltraISR kit data sheet (CY3700i).

Third-Party Programmers

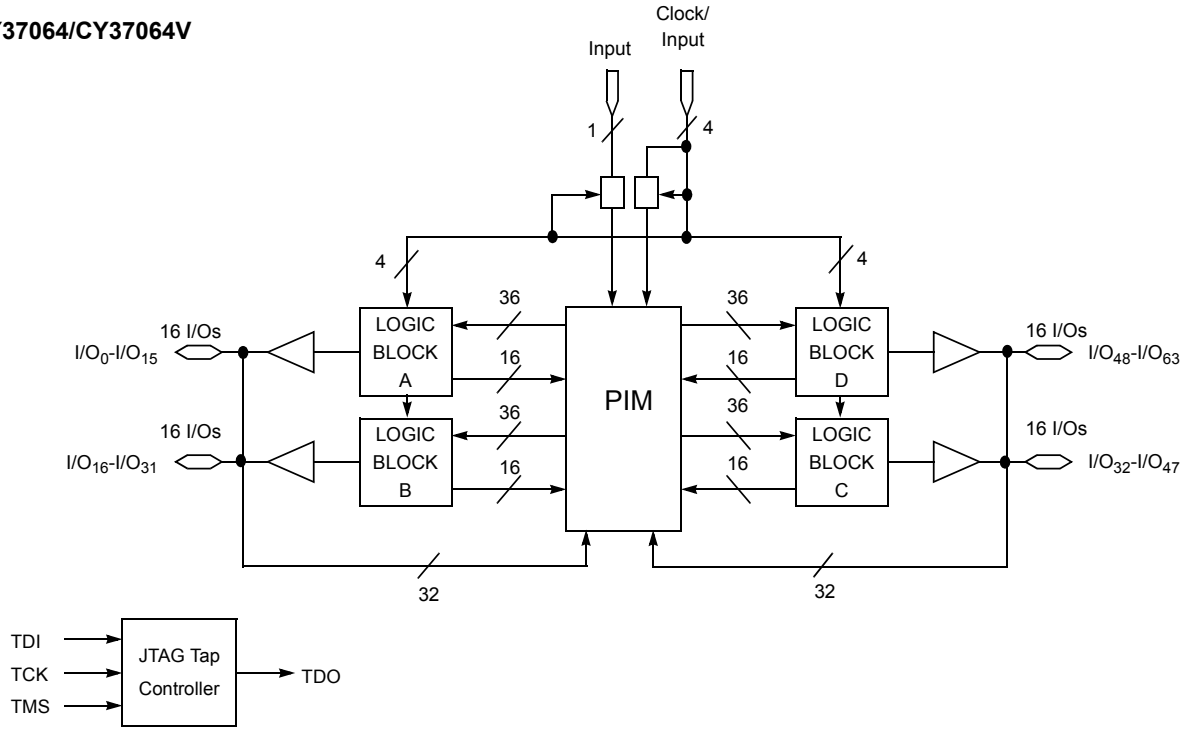
As with development software, Cypress support is available on a wide variety of third-party programmers. All major third-party programmers (including BP Micro, Data I/O, and SMS) support the Ultra37000 family.

Logic Block Diagrams

CY37032/CY37032V

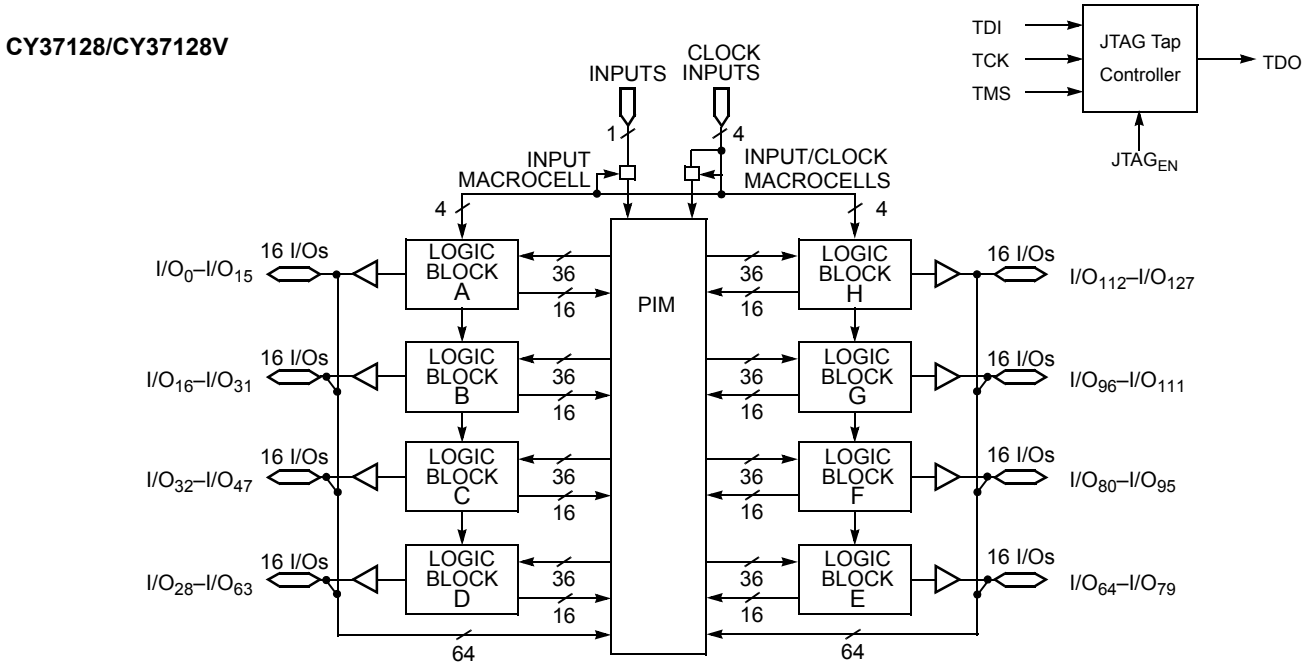


CY37064/CY37064V

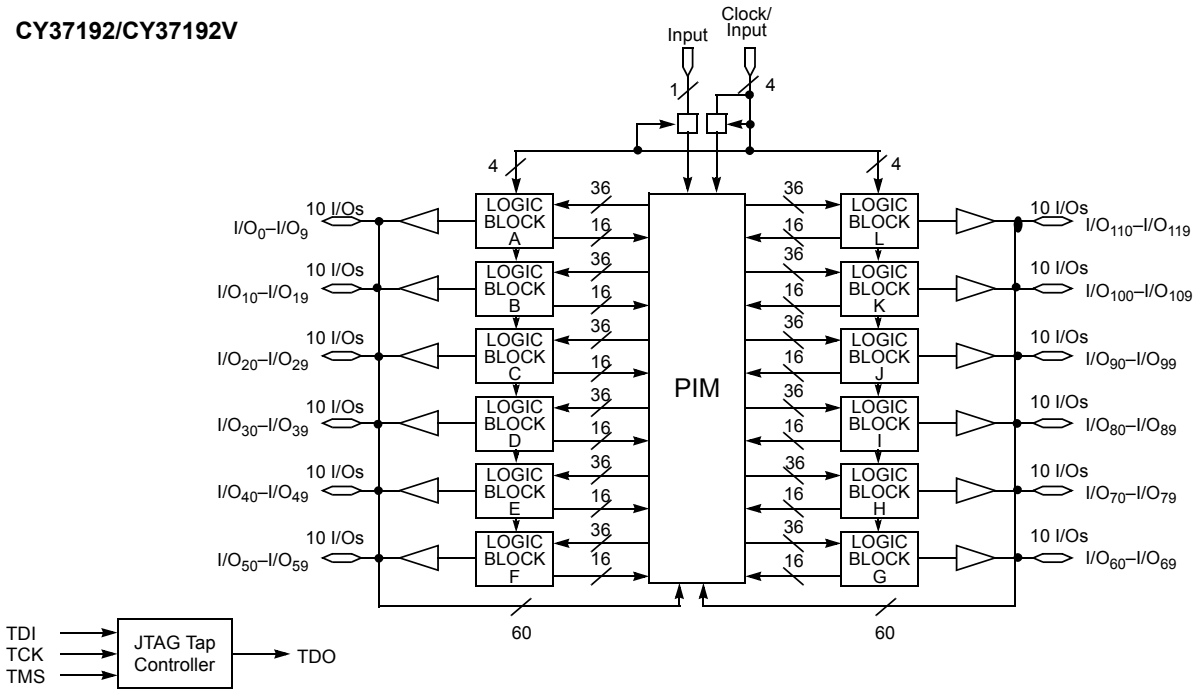


Logic Block Diagrams (continued)

CY37128/CY37128V



CY37192/CY37192V



Inductance[5]

Parameter	Description	Test Conditions	44-Lead TQFP	44-Lead PLCC	44-Lead CLCC	84-Lead PLCC	84-Lead CLCC	100-Lead TQFP	160-Lead TQFP	208-Lead PQFP	Unit
L	Maximum Pin Inductance	V_{IN} = 5.0V at f = 1 MHz	2	5	2	8	5	8	9	11	nH

Capacitance[5]

Parameter	Description	Test Conditions	Max.	Unit
$C_{I/O}$	Input/Output Capacitance	V_{IN} = 5.0V at f = 1 MHz at T_A = 25°C	10	pF
C_{CLK}	Clock Signal Capacitance	V_{IN} = 5.0V at f = 1 MHz at T_A = 25°C	12	pF
C_{DP}	Dual-Function Pins[9]	V_{IN} = 5.0V at f = 1 MHz at T_A = 25°C	16	pF

Endurance Characteristics[5]

Parameter	Description	Test Conditions	Min.	Typ.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions[2]	1,000	10,000	Cycles

3.3V Device Characteristics Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... –65°C to +150°C

Ambient Temperature with Power Applied ..... –55°C to +125°C

Supply Voltage to Ground Potential ..... –0.5V to +4.6V

DC Voltage Applied to Outputs in High-Z State ..... –0.5V to +7.0V

DC Input Voltage ..... –0.5V to +7.0V

DC Program Voltage ..... 3.0 to 3.6V

Current into Outputs ..... 8 mA

Static Discharge Voltage ..... > 2001V (per MIL-STD-883, Method 3015)

Latch-up Current ..... > 200 mA

Operating Range[2]

Range	Ambient Temperature[2]	Junction Temperature	V_{CC}[10]
Commercial	0°C to +70°C	0°C to +90°C	3.3V ± 0.3V
Industrial	–40°C to +85°C	–40°C to +105°C	3.3V ± 0.3V
Military[3]	–55°C to +125°C	–55°C to +130°C	3.3V ± 0.3V

3.3V Device Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min.	I_{OH} = –4 mA (Com'l)[4]	2.4		V
			I_{OH} = –3 mA (Mil)[4]			
V_{OL}	Output LOW Voltage	V_{CC} = Min.	I_{OL} = 8 mA (Com'l)[4]		0.5	V
			I_{OL} = 6 mA (Mil)[4]			
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs[7]		2.0	5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs[7]		–0.5	0.8	V
I_{IX}	Input Load Current	V_I = GND OR V_{CC}, Bus-Hold Disabled		–10	10	µA
I_{OZ}	Output Leakage Current	V_O = GND or V_{CC}, Output Disabled, Bus-Hold Disabled		–50	50	µA
I_{OS}	Output Short Circuit Current[5, 8]	V_{CC} = Max., V_{OUT} = 0.5V		–30	–160	mA
I_{BHL}	Input Bus-Hold LOW Sustaining Current	V_{CC} = Min., V_{IL} = 0.8V		+75		µA
I_{BHH}	Input Bus-Hold HIGH Sustaining Current	V_{CC} = Min., V_{IH} = 2.0V		–75		µA
I_{BHLO}	Input Bus-Hold LOW Overdrive Current	V_{CC} = Max.			+500	µA
I_{BHHO}	Input Bus-Hold HIGH Overdrive Current	V_{CC} = Max.			–500	µA

Notes:
9. Dual pins are I/O with JTAG pins.
10. For CY37064VP100-143AC, CY37064VP100-143BBC, CY37064VP44-143AC, CY37064VP48-143BAC; Operating Range: V_{CC} is 3.3V± 0.16V.

Inductance[5]

Parameter	Description	Test Conditions	44-Lead TQFP	44-Lead PLCC	44-Lead CLCC	84-Lead PLCC	84-Lead CLCC	100-Lead TQFP	160-Lead TQFP	208-Lead PQFP	Unit
L	Maximum Pin Inductance	V_{IN} = 3.3V at f = 1 MHz	2	5	2	8	5	8	9	11	nH

Capacitance[5]

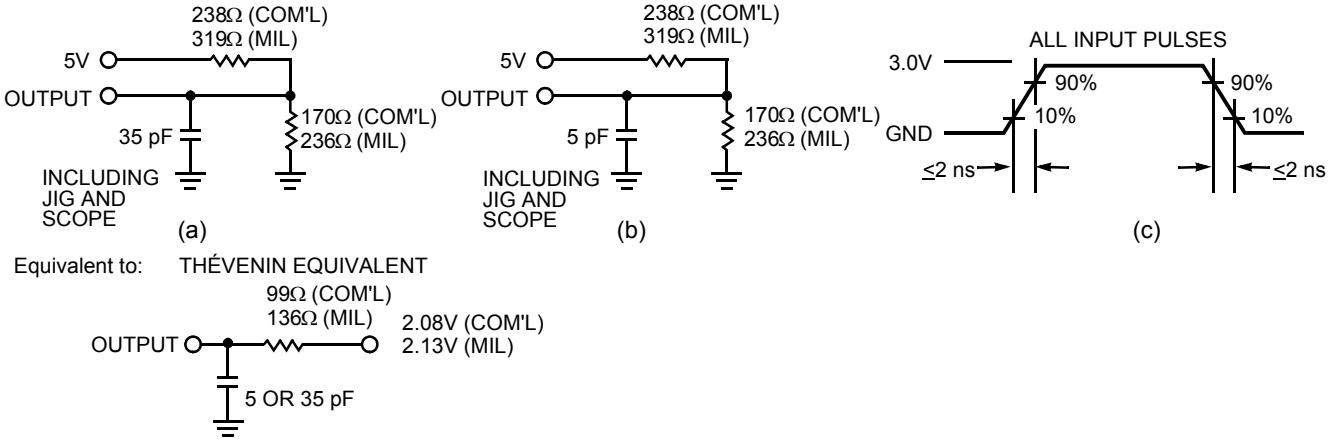
Parameter	Description	Test Conditions	Max.	Unit
$C_{I/O}$	Input/Output Capacitance	V_{IN} = 3.3V at f = 1 MHz at T_A = 25°C	8	pF
C_{CLK}	Clock Signal Capacitance	V_{IN} = 3.3V at f = 1 MHz at T_A = 25°C	12	pF
C_{DP}	Dual Functional Pins[9]	V_{IN} = 3.3V at f = 1 MHz at T_A = 25°C	16	pF

Endurance Characteristics[5]

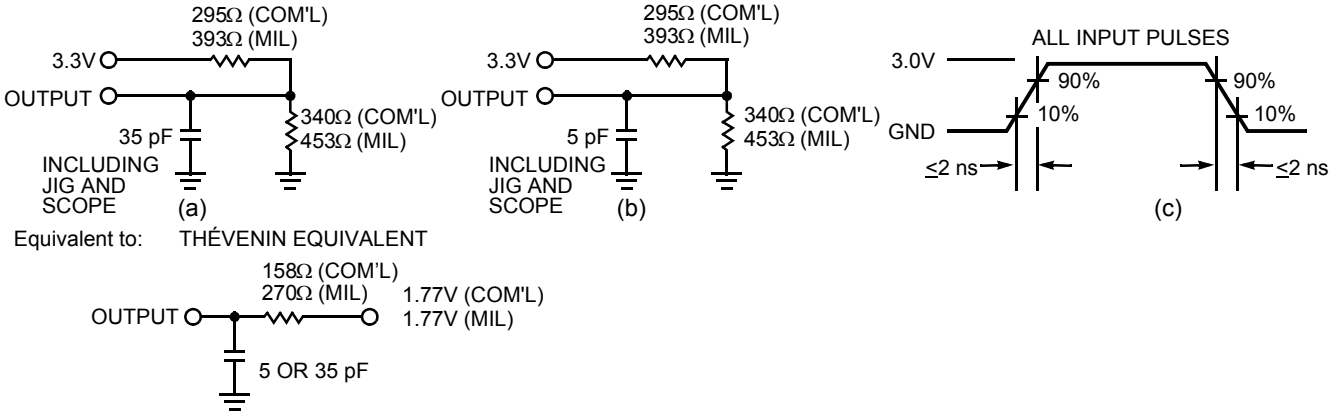
Parameter	Description	Test Conditions	Min.	Typ.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions[2]	1,000	10,000	Cycles

AC Characteristics

5.0V AC Test Loads and Waveforms



3.3V AC Test Loads and Waveforms



Switching Characteristics Over the Operating Range (continued)[12]

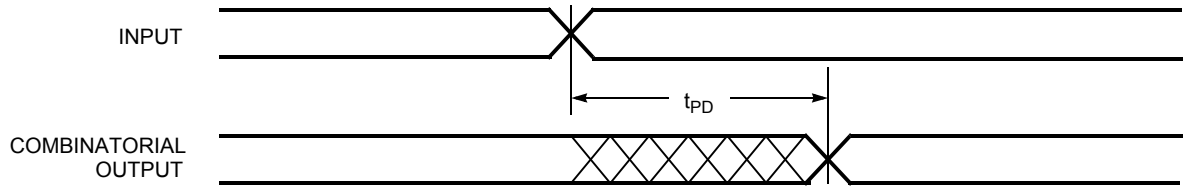
Parameter	Description	Unit
Product Term Clocking Parameters		
t_{COPT}[13, 14, 15]	Product Term Clock or Latch Enable (PTCLK) to Output	ns
t_{SPT}	Set-Up Time from Input to Product Term Clock or Latch Enable (PTCLK)	ns
t_{HPT}	Register or Latch Data Hold Time	ns
t_{ISPT}[13]	Set-Up Time for Buried Register used as an Input Register from Input to Product Term Clock or Latch Enable (PTCLK)	ns
t_{IHPT}	Buried Register Used as an Input Register or Latch Data Hold Time	ns
t_{CO2PT}[13, 14, 15]	Product Term Clock or Latch Enable (PTCLK) to Output Delay (Through Logic Array)	ns
Pipelined Mode Parameters		
t_{ICS}[13]	Input Register Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) to Output Register Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3)	ns
Operating Frequency Parameters		
f_{MAX1}	Maximum Frequency with Internal Feedback (Lesser of $1/t_{SCS}$, $1/(t_S + t_H)$, or $1/t_{CO}$)[5]	MHz
f_{MAX2}	Maximum Frequency Data Path in Output Registered/Latched Mode (Lesser of $1/(t_{WL} + t_{WH})$, $1/(t_S + t_H)$, or $1/t_{CO}$)[5]	MHz
f_{MAX3}	Maximum Frequency with External Feedback (Lesser of $1/(t_{CO} + t_S)$ or $1/(t_{WL} + t_{WH})$[5]	MHz
f_{MAX4}	Maximum Frequency in Pipelined Mode (Lesser of $1/(t_{CO} + t_{IS})$, $1/t_{ICS}$, $1/(t_{WL} + t_{WH})$, $1/(t_{IS} + t_{IH})$, or $1/t_{SCS}$)[5]	MHz
Reset/Preset Parameters		
t_{RW}	Asynchronous Reset Width[5]	ns
t_{RR}[13]	Asynchronous Reset Recovery Time[5]	ns
t_{RO}[13, 14, 15]	Asynchronous Reset to Output	ns
t_{PW}	Asynchronous Preset Width[5]	ns
t_{PR}[13]	Asynchronous Preset Recovery Time[5]	ns
t_{PO}[13, 14, 15]	Asynchronous Preset to Output	ns
User Option Parameters		
t_{LP}	Low Power Adder	ns
t_{SLEW}	Slow Output Slew Rate Adder	ns
$t_{3.3IO}$	3.3V I/O Mode Timing Adder[5]	ns
JTAG Timing Parameters		
$t_{S\ JTAG}$	Set-up Time from TDI and TMS to TCK[5]	ns
$t_{H\ JTAG}$	Hold Time on TDI and TMS[5]	ns
$t_{CO\ JTAG}$	Falling Edge of TCK to TDO[5]	ns
f_{JTAG}	Maximum JTAG Tap Controller Frequency[5]	ns

Switching Characteristics Over the Operating Range (continued)[12]

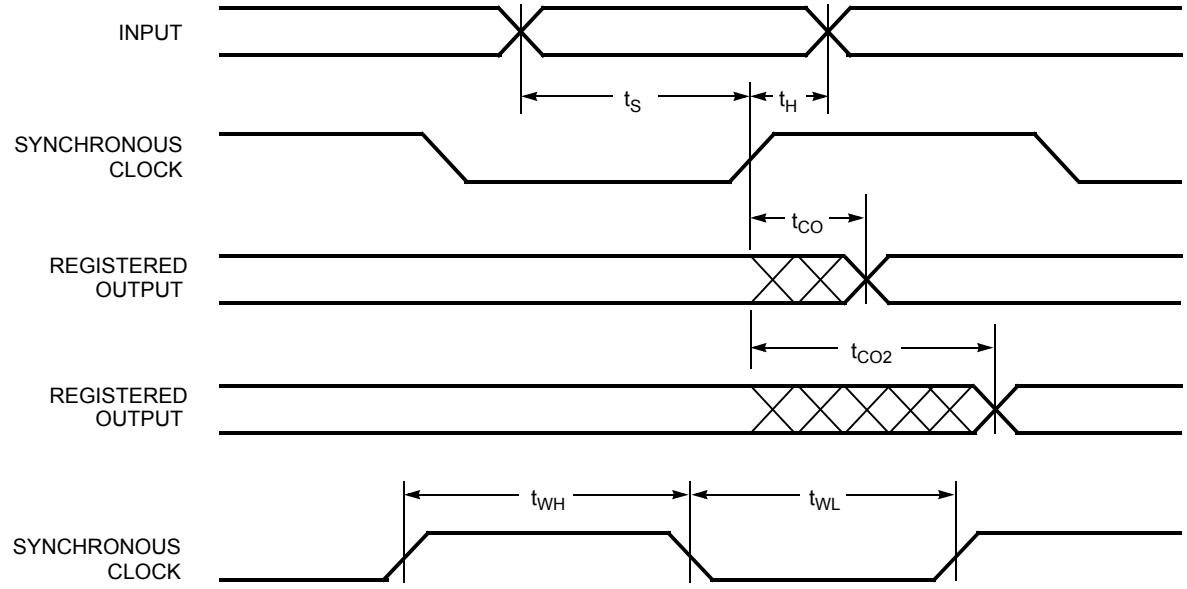
Parameter	200 MHz		167 MHz		154 MHz		143 MHz		125 MHz		100 MHz		83 MHz		66 MHz		Unit
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{RO}[13, 14, 15]		12		13		13		14		15		18		21		26	ns
t_{PW}	8		8		8		8		10		12		15		20		ns
t_{PR}[13]	10		10		10		10		12		14		17		22		ns
t_{PO}[13, 14, 15]		12		13		13		14		15		18		21		26	ns
User Option Parameters																	
t_{LP}		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t_{SLEW}		3		3		3		3		3		3		3		3	ns
$t_{3.3IO}$[19]		0.3		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
JTAG Timing Parameters																	
$t_{S\ JTAG}$	0		0		0		0		0		0		0		0		ns
$t_{H\ JTAG}$	20		20		20		20		20		20		20		20		ns
$t_{CO\ JTAG}$		20		20		20		20		20		20		20		20	ns
f_{JTAG}		20		20		20		20		20		20		20		20	MHz

Switching Waveforms

Combinatorial Output



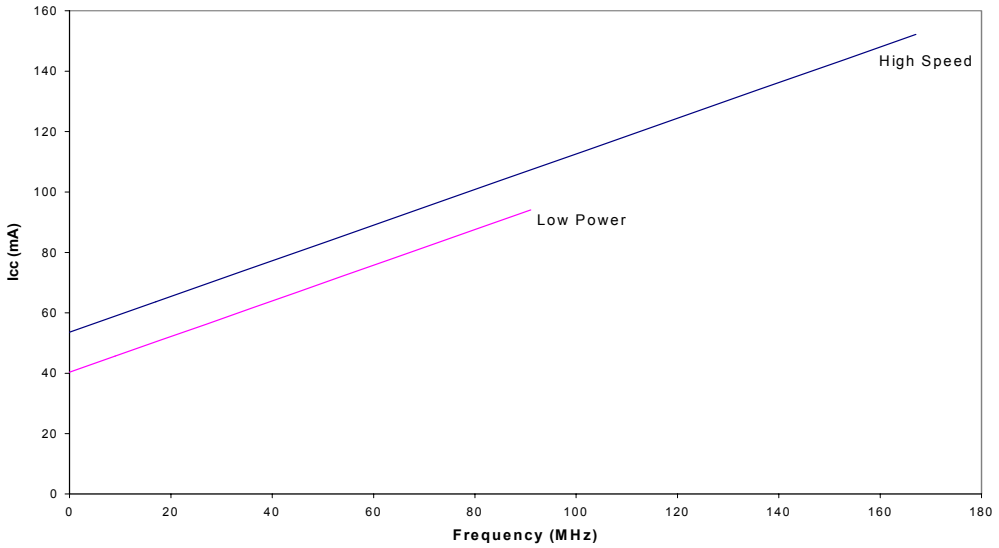
Registered Output with Synchronous Clocking



Note:
19. Only applicable to the 5V devices.

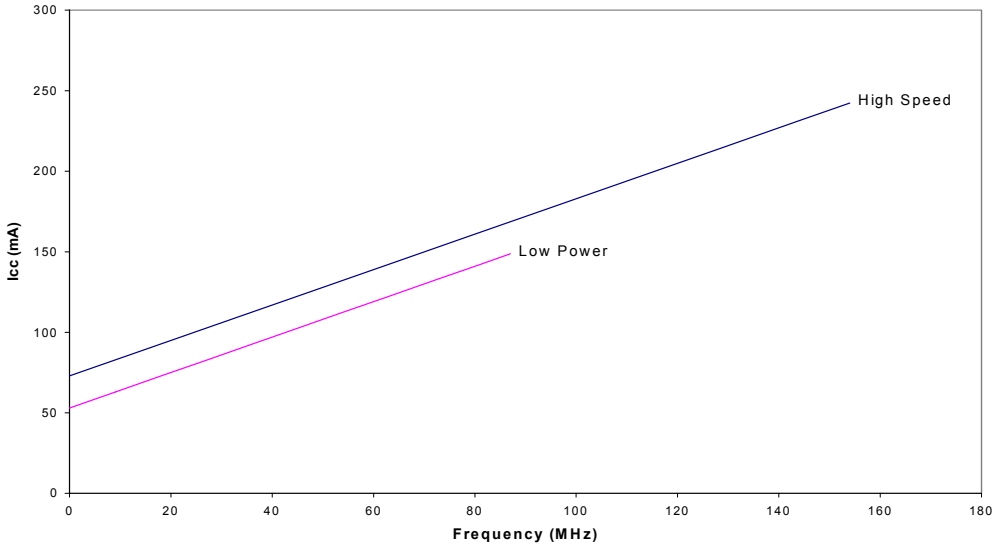
Typical 5.0V Power Consumption (continued)

CY37128



The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 5.0V, T_A = Room Temperature

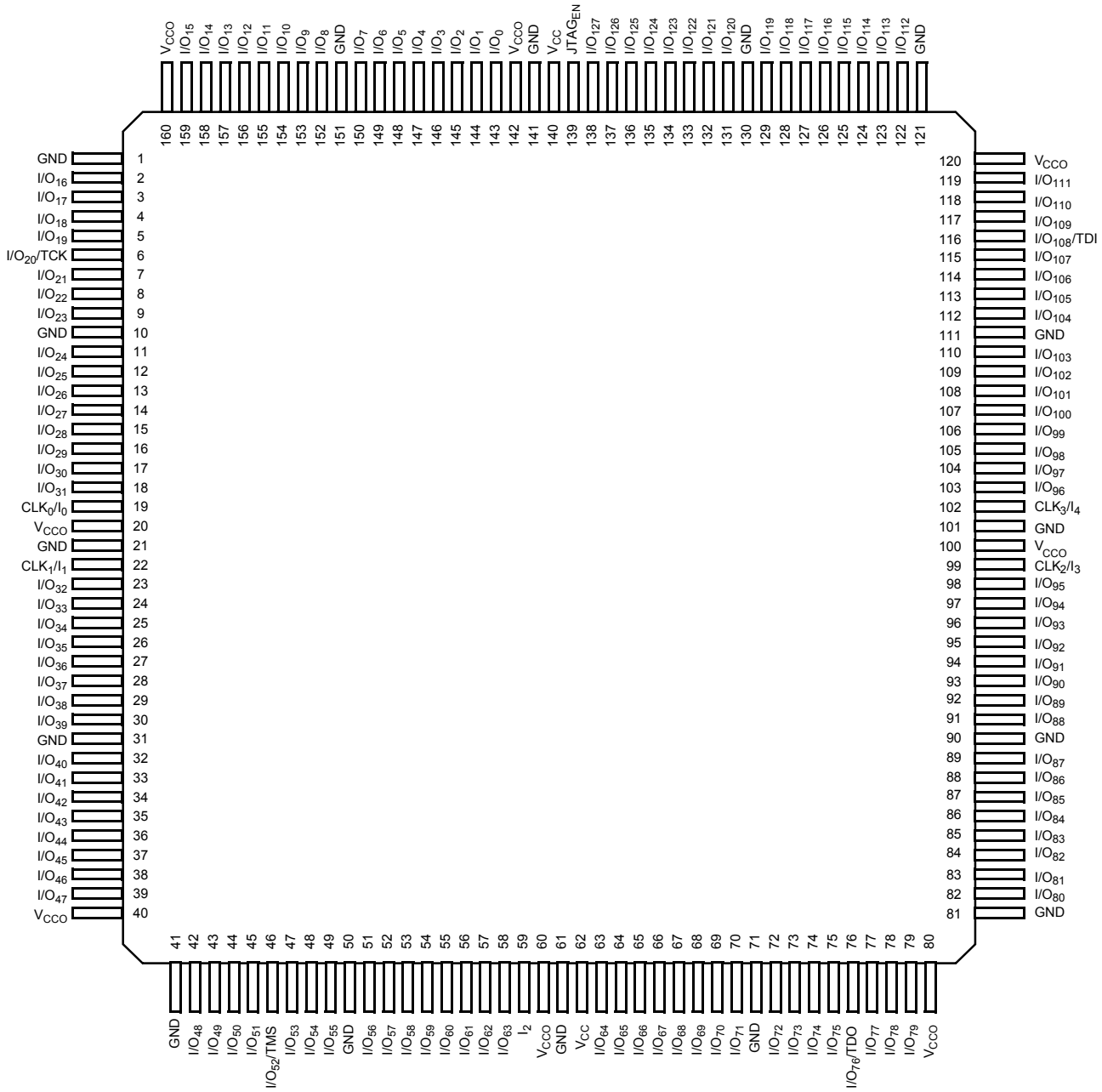
CY37192



The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 5.0V, T_A = Room Temperature

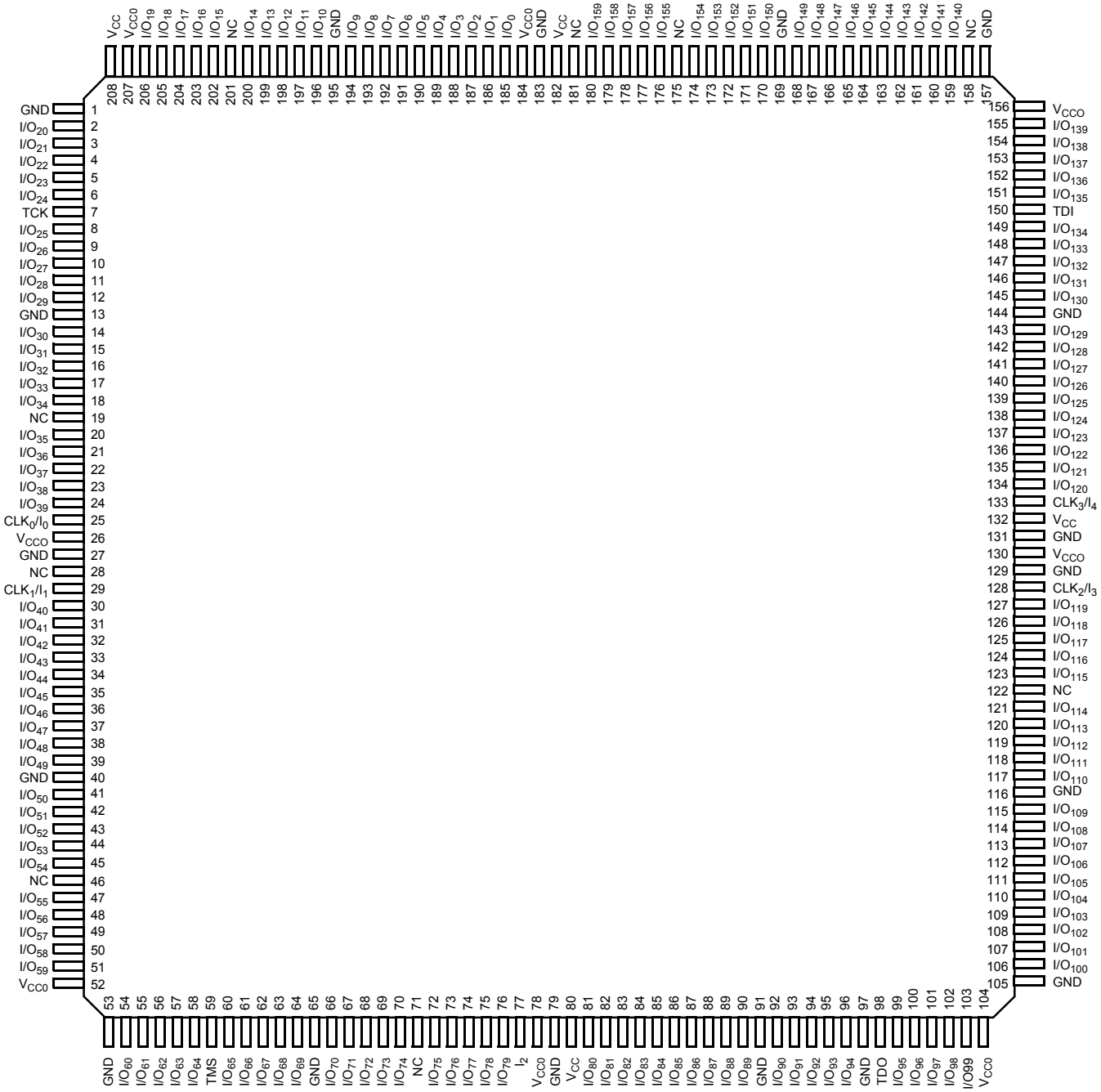
Pin Configurations[20] (continued)

160-Lead TQFP (A160) / CQFP (U162)
for CY37128(V) and CY37256(V)
Top View



Pin Configurations[20] (continued)

208-Lead PQFP (N208) / CQFP (U208)
Top View



Pin Configurations[20] (continued)

292-Ball PBGA (BG292)
Top View

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	GND	I/O_{21}	NC	I/O_{16}	I/O_{12}	I/O_{9}	I/O_{7}	I/O_{4}	I/O_{0}	I/O_{190}	I/O_{189}	I/O_{186}	I/O_{182}	NC	I/O_{178}	I/O_{175}	NC	NC	I/O_{169}	I/O_{168}	A
B	I/O_{23}	I/O_{20}	I/O_{19}	I/O_{18}	I/O_{15}	I/O_{11}	I/O_{8}	I/O_{5}	I/O_{1}	I/O_{191}	I/O_{187}	I/O_{185}	I/O_{181}	NC	NC	I/O_{174}	I/O_{171}	I/O_{170}	NC	I/O_{166}	B
C	NC	NC	I/O_{22}	NC	I/O_{17}	I/O_{14}	I/O_{10}	I/O_{6}	I/O_{2}	NC	I/O_{188}	I/O_{184}	I/O_{180}	I/O_{179}	I/O_{176}	I/O_{173}	I/O_{172}	I/O_{167}	I/O_{165}	I/O_{162}	C
D	I/O_{24}	NC	NC	GND	NC	V_{CCO}	I/O_{13}	GND	I/O_{3}	NC	V_{CC}	I/O_{183}	GND	I/O_{177}	V_{CCO}	NC	GND	I/O_{164}	TDI	I/O_{160}	D
E	I/O_{27}	I/O_{26}	I/O_{25}	NC													I/O_{163}	I/O_{161}	I/O_{159}	I/O_{156}	E
F	I/O_{30}	TCK	I/O_{28}	V_{CCO}													V_{CCO}	I/O_{158}	NC	I/O_{154}	F
G	I/O_{33}	I/O_{32}	I/O_{31}	I/O_{29}													I/O_{157}	I/O_{155}	I/O_{153}	I/O_{152}	G
H	I/O_{35}	NC	I/O_{34}	GND				GND	GND	GND	GND	GND	GND				GND	I/O_{151}	I/O_{150}	I/O_{149}	H
J	I/O_{39}	I/O_{38}	I/O_{37}	I/O_{36}				GND	GND	GND	GND	GND	GND				I/O_{148}	I/O_{147}	I/O_{146}	I/O_{145}	J
K	I/O_{42}	I/O_{40}	I/O_{41}	V_{CC}				GND	GND	GND	GND	GND	GND				I/O_{144}	CLK_3/I_4	NC	NC	K
L	I/O_{43}	I/O_{44}	I/O_{45}	I/O_{46}				GND	GND	GND	GND	GND	GND				V_{CC}	CLK_2/I_3	I/O_{143}	NC	L
M	I/O_{47}	CLK_0/I_0	CLK_1/I_1	I/O_{48}				GND	GND	GND	GND	GND	GND				I/O_{139}	I/O_{140}	I/O_{141}	I/O_{142}	M
N	I/O_{49}	I/O_{50}	I/O_{51}	GND				GND	GND	GND	GND	GND	GND				GND	I/O_{136}	I/O_{137}	I/O_{138}	N
P	I/O_{52}	I/O_{53}	I/O_{55}	I/O_{58}													I/O_{131}	I/O_{133}	I/O_{134}	I/O_{135}	P
R	I/O_{54}	I/O_{56}	I/O_{59}	V_{CCO}													V_{CCO}	I/O_{130}	NC	I/O_{132}	R
T	I/O_{57}	I/O_{60}	I/O_{62}	I/O_{65}													I/O_{124}	I/O_{127}	I/O_{128}	I/O_{129}	T
U	I/O_{61}	I/O_{63}	I/O_{66}	GND	I/O_{76}	V_{CCO}	I/O_{82}	GND	I/O_{91}	V_{CC}	I/O_{98}	I/O_{102}	GND	I/O_{112}	V_{CCO}	NC	GND	I/O_{123}	I/O_{122}	I/O_{126}	U
V	I/O_{64}	I/O_{67}	I/O_{69}	I/O_{75}	I/O_{78}	I/O_{81}	I/O_{85}	I/O_{88}	I/O_{92}	I_2	I/O_{97}	I/O_{101}	I/O_{105}	I/O_{109}	I/O_{113}	TDO	I/O_{114}	I/O_{117}	I/O_{121}	I/O_{125}	V
W	I/O_{68}	I/O_{70}	I/O_{72}	I/O_{74}	I/O_{79}	I/O_{83}	I/O_{86}	I/O_{89}	I/O_{93}	I/O_{95}	I/O_{96}	I/O_{100}	I/O_{104}	I/O_{107}	I/O_{110}	NC	NC	I/O_{115}	I/O_{118}	I/O_{120}	W
Y	I/O_{71}	I/O_{73}	I/O_{77}	TMS	I/O_{80}	I/O_{84}	I/O_{87}	I/O_{90}	I/O_{94}	NC	NC	I/O_{99}	I/O_{103}	I/O_{106}	I/O_{108}	I/O_{111}	NC	NC	I/O_{116}	I/O_{119}	Y
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	

Pin Configurations[20] (continued)

400-Ball Fine-Pitch BGA (BB400)

Top View

A	GND	GND	NC	I/O_{17}	I/O_{16}	I/O_{14}	I/O_{29}	V_{CC}	I/O_{11}	GND	GND	I/O_{257}	V_{CC}	I/O_{239}	I/O_{233}	I/O_{232}	I/O_{230}	NC	GND	GND
B	GND	GND	GND	NC	I/O_{15}	I/O_{13}	I/O_{28}	V_{CC}	I/O_{10}	GND	GND	I/O_{256}	V_{CC}	I/O_{238}	I/O_{231}	I/O_{229}	NC	GND	GND	GND
C	NC	GND	GND	GND	I/O_{20}	I/O_{12}	I/O_{27}	V_{CC}	I/O_{9}	GND	GND	I/O_{255}	V_{CC}	I/O_{237}	I/O_{228}	I/O_{245}	GND	GND	GND	NC
D	I/O_{44}	NC	GND	I/O_{21}	I/O_{19}	I/O_{18}	I/O_{26}	I/O_{25}	I/O_{8}	GND	GND	I/O_{254}	I/O_{235}	I/O_{236}	I/O_{251}	I/O_{244}	I/O_{243}	GND	NC	I/O_{227}
E	I/O_{46}	I/O_{43}	I/O_{23}	I/O_{22}	NC	I/O_{35}	I/O_{34}	I/O_{24}	I/O_{7}	I/O_{4}	I/O_{263}	I/O_{253}	I/O_{234}	I/O_{250}	I/O_{248}	NC	I/O_{241}	I/O_{242}	I/O_{225}	I/O_{226}
F	I/O_{47}	I/O_{45}	I/O_{42}	I/O_{41}	I/O_{40}	NC	I/O_{33}	I/O_{32}	I/O_{6}	I/O_{3}	I/O_{262}	I/O_{252}	I/O_{249}	I/O_{247}	I/O_{220}	I/O_{221}	I/O_{240}	I/O_{222}	I/O_{223}	I/O_{224}
G	I/O_{53}	I/O_{52}	I/O_{51}	I/O_{50}	I/O_{39}	I/O_{38}	I/O_{37}	I/O_{31}	I/O_{5}	I/O_{2}	I/O_{261}	V_{CC}	I/O_{246}	I/O_{217}	I/O_{218}	I/O_{219}	I/O_{212}	I/O_{213}	I/O_{214}	I/O_{215}
H	V_{CC}	V_{CC}	V_{CC}	I/O_{49}	I/O_{48}	I/O_{36}	TCK	V_{CC}	I/O_{30}	I/O_{1}	I/O_{259}	I/O_{260}	V_{CC}	TDI	I/O_{216}	I/O_{210}	I/O_{211}	V_{CC}	V_{CC}	V_{CC}
J	I/O_{59}	I/O_{58}	I/O_{57}	I/O_{56}	I/O_{55}	I/O_{54}	V_{CC}	I/O_{62}	I/O_{60}	I/O_{0}	I/O_{258}	I/O_{202}	I/O_{203}	CLK_3 /I_4	I/O_{204}	I/O_{205}	I/O_{206}	I/O_{207}	I/O_{208}	I/O_{209}
K	GND	GND	GND	GND	I/O_{65}	I/O_{64}	CLK_0 /I_0	I/O_{63}	I/O_{61}	GND	GND	I/O_{198}	I/O_{199}	CLK_2 /I_3	I/O_{200}	I/O_{201}	GND	GND	GND	GND
L	GND	GND	GND	GND	I/O_{69}	I/O_{68}	NC	I/O_{67}	I/O_{66}	GND	GND	I/O_{193}	I/O_{195}	I_2	I/O_{196}	I/O_{197}	GND	GND	GND	GND
M	I/O_{89}	I/O_{88}	I/O_{87}	I/O_{86}	I/O_{85}	I/O_{84}	CLK_1 /I_1	I/O_{71}	I/O_{70}	I/O_{126}	I/O_{132}	I/O_{192}	I/O_{194}	V_{CC}	I/O_{174}	I/O_{175}	I/O_{176}	I/O_{177}	I/O_{178}	I/O_{179}
N	V_{CC}	V_{CC}	V_{CC}	I/O_{91}	I/O_{90}	I/O_{72}	TMS	V_{CC}	I/O_{128}	I/O_{127}	I/O_{133}	I/O_{162}	V_{CC}	TDO	I/O_{180}	I/O_{168}	I/O_{169}	V_{CC}	V_{CC}	V_{CC}
P	I/O_{95}	I/O_{94}	I/O_{93}	I/O_{92}	I/O_{75}	I/O_{74}	I/O_{73}	I/O_{114}	V_{CC}	I/O_{129}	I/O_{134}	I/O_{137}	I/O_{163}	I/O_{181}	I/O_{182}	I/O_{183}	I/O_{170}	I/O_{171}	I/O_{172}	I/O_{173}
R	I/O_{80}	I/O_{79}	I/O_{78}	I/O_{108}	I/O_{77}	I/O_{76}	I/O_{115}	I/O_{117}	I/O_{120}	I/O_{130}	I/O_{135}	I/O_{138}	I/O_{164}	I/O_{165}	NC	I/O_{184}	I/O_{185}	I/O_{186}	I/O_{189}	I/O_{191}
T	I/O_{82}	I/O_{81}	I/O_{110}	I/O_{109}	NC	I/O_{116}	I/O_{118}	I/O_{102}	I/O_{121}	I/O_{131}	I/O_{136}	I/O_{139}	I/O_{156}	I/O_{166}	I/O_{167}	NC	I/O_{154}	I/O_{155}	I/O_{187}	I/O_{190}
U	I/O_{83}	NC	GND	I/O_{111}	I/O_{112}	I/O_{119}	I/O_{104}	I/O_{103}	I/O_{122}	GND	GND	I/O_{140}	I/O_{157}	I/O_{158}	I/O_{150}	I/O_{151}	I/O_{153}	GND	NC	I/O_{188}
V	NC	GND	GND	GND	I/O_{113}	I/O_{96}	I/O_{105}	V_{CC}	I/O_{123}	GND	GND	I/O_{141}	V_{CC}	I/O_{159}	I/O144	I/O_{152}	GND	GND	GND	NC
W	GND	GND	GND	NC	I/O_{97}	I/O_{99}	I/O_{106}	V_{CC}	I/O_{124}	GND	GND	I/O_{142}	V_{CC}	I/O_{160}	I/O_{145}	I/O_{147}	NC	GND	GND	GND
Y	GND	GND	NC	I/O_{98}	I/O_{100}	I/O_{101}	I/O_{107}	V_{CC}	I/O_{125}	GND	GND	I/O_{143}	V_{CC}	I/O_{161}	I/O_{146}	I/O_{148}	I/O_{149}	NC	GND	GND

5.0V Ordering Information (continued)

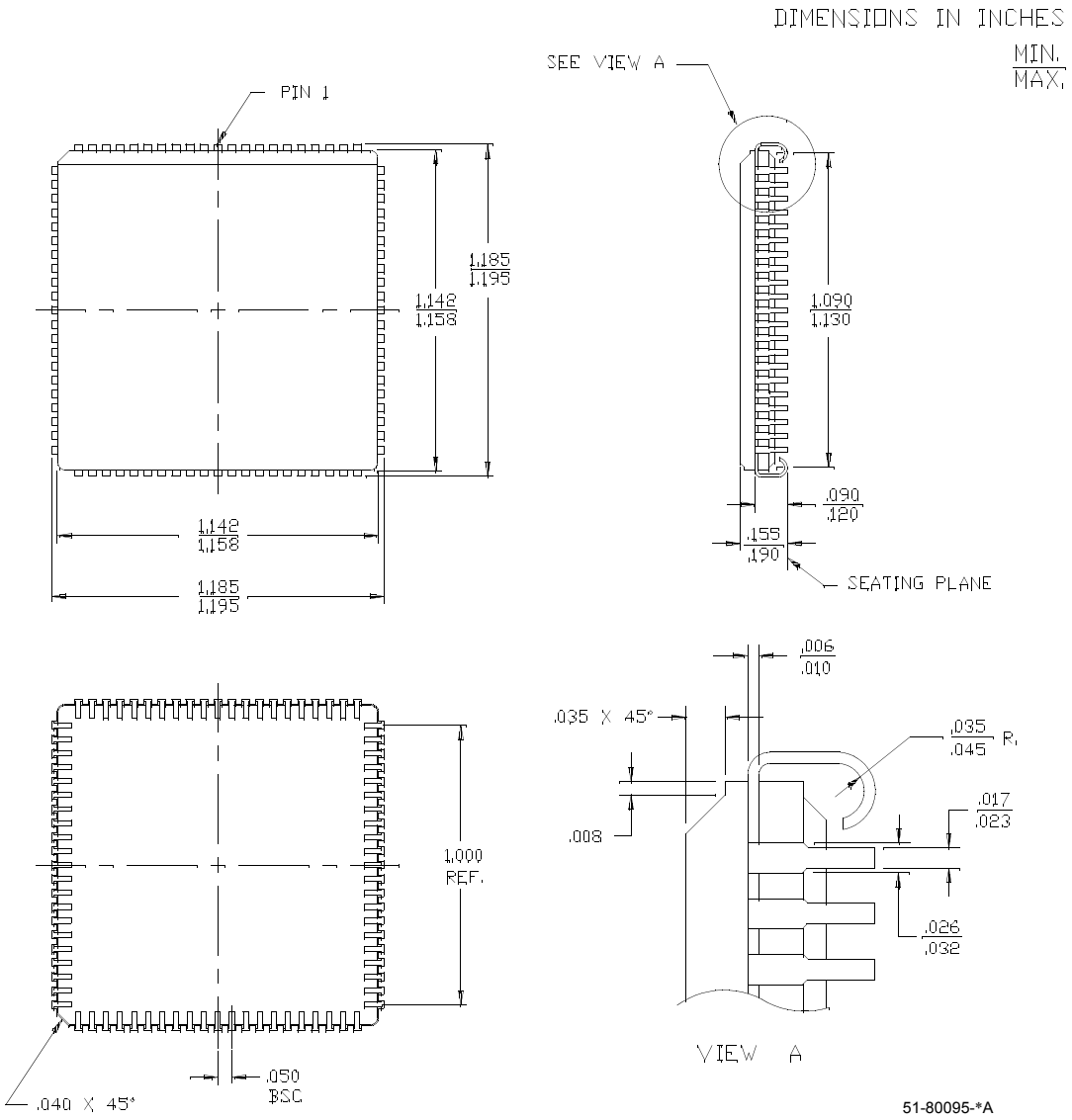
Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
64	154	CY37064P44-154AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37064P44-154JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37064P84-154JC	J83	84-Lead Plastic Leaded Chip Carrier	
		CY37064P100-154AC	A100	100-Lead Thin Quad Flat Pack	
		CY37064P44-154AI	A44	44-Lead Thin Quad Flat Pack	Industrial
		CY37064P44-154AXI	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37064P44-154JI	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37064P44-154JXI	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37064P84-154JI	J83	84-Lead Plastic Leaded Chip Carrier	
		CY37064P100-154AI	A100	100-Lead Thin Quad Flat Pack	
		5962-9951902QYA	Y67	44-Lead Ceramic Leadless Chip Carrier	Military
	125	CY37064P44-125AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37064P44-125AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37064P44-125JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37064P44-125JXC	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37064P84-125JC	J83	84-Lead Plastic Leaded Chip Carrier	
		CY37064P100-125AC	A100	100-Lead Thin Quad Flat Pack	
		CY37064P100-125AXC	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37064P44-125AI	A44	44-Lead Thin Quad Flat Pack	Industrial
		CY37064P44-125AXI	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37064P44-125JI	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37064P84-125JI	J83	84-Lead Plastic Leaded Chip Carrier	
		CY37064P100-125AI	A100	100-Lead Thin Quad Flat Pack	
		CY37064P100-125AXI	A100	100-Lead Lead Free Thin Quad Flat Pack	
		5962-9951901QYA	Y67	44-Lead Ceramic Leadless Chip Carrier	Military

5.0V Ordering Information (continued)

Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
256	154	CY37256P160-154AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37256P160-154AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37256P208-154NC	N208	208-Lead Plastic Quad Flat Pack	
		CY37256P256-154BGC	BG292	292-Ball Plastic Ball Grid Array	
	125	CY37256P160-125AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37256P160-125AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37256P208-125NC	N208	208-Lead Plastic Quad Flat Pack	
		CY37256P256-125BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37256P160-125AI	A160	160-Lead Thin Quad Flat Pack	Industrial
		CY37256P160-125AXI	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37256P208-125NI	N208	208-Lead Plastic Quad Flat Pack	
		CY37256P256-125BGI	BG292	292-Ball Plastic Ball Grid Array	
		5962-9952302QZC	U162	160-Lead Ceramic Quad Flat Pack	Military
	83	CY37256P160-83AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37256P160-83AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37256P208-83NC	N208	208-Lead Plastic Quad Flat Pack	
		CY37256P256-83BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37256P160-83AI	A160	160-Lead Thin Quad Flat Pack	Industrial
		CY37256P160-83AXI	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37256P208-83NI	N208	208-Lead Plastic Quad Flat Pack	
		CY37256P256-83BGI	BG292	292-Ball Plastic Ball Grid Array	
		5962-9952301QZC	U162	160-Lead Ceramic Quad Flat Pack	Military
384	125	CY37384P208-125NC	N208	208-Lead Plastic Quad Flat Pack	Commercial
		CY37384P256-125BGC	BG292	292-Ball Plastic Ball Grid Array	
	83	CY37384P208-83NC	N208	208-Lead Plastic Quad Flat Pack	Commercial
		CY37384P256-83BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37384P208-83NI	N208	208-Lead Plastic Quad Flat Pack	Industrial
		CY37384P256-83BGI	BG292	292-Ball Plastic Ball Grid Array	

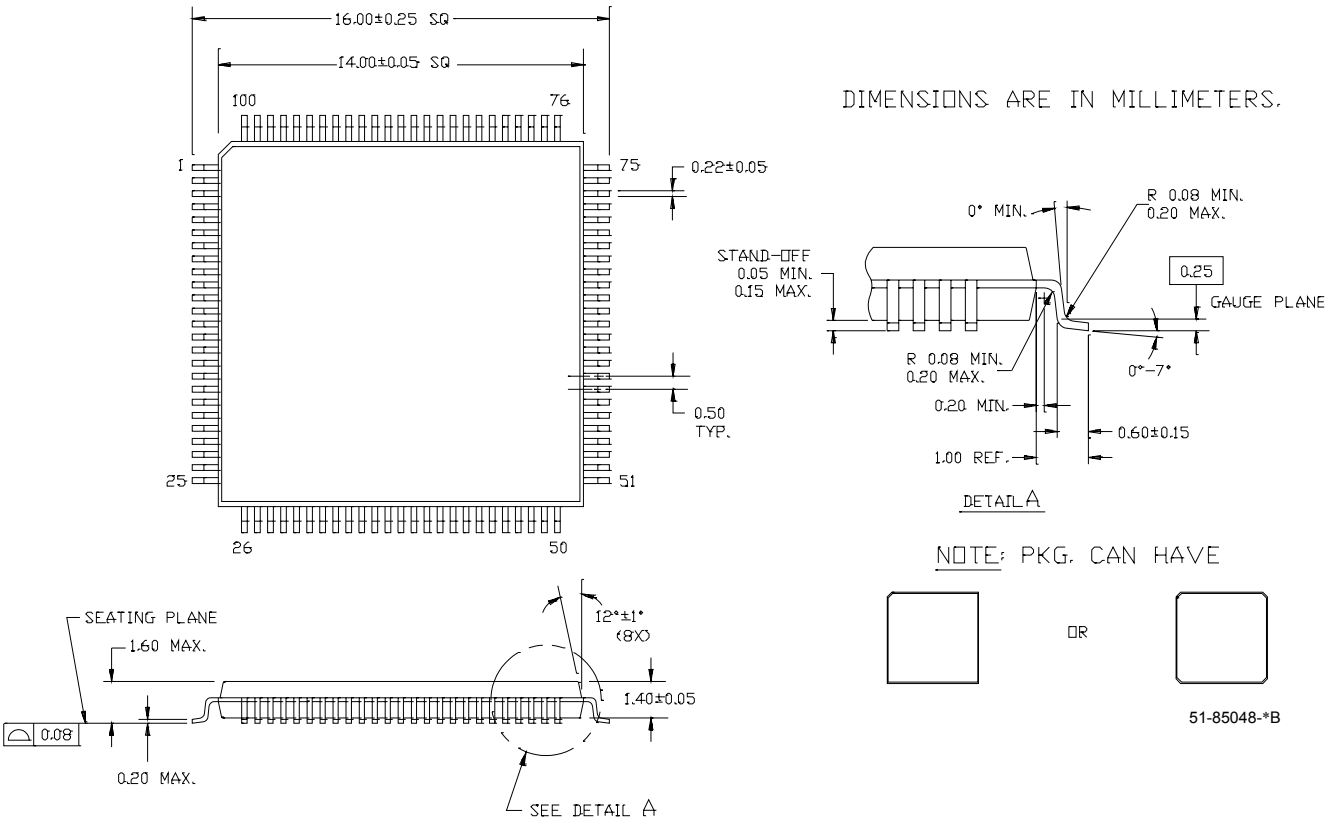
Package Diagrams (continued)

84-Lead Ceramic Leaded Chip Carrier Y84



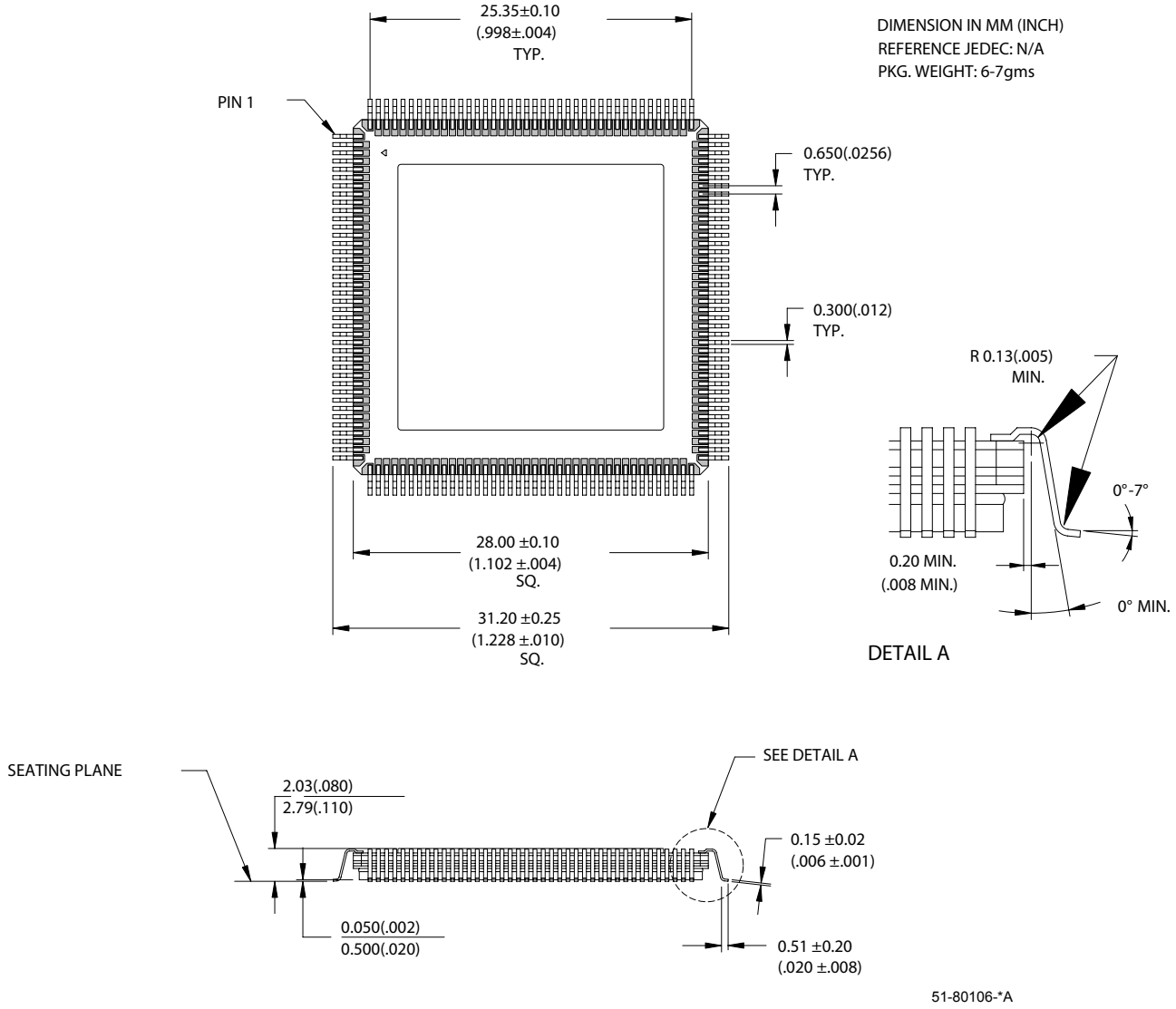
Package Diagrams (continued)

100-Lead Lead (Pb)-Free Thin Plastic Quad Flat Pack (TQFP) A100



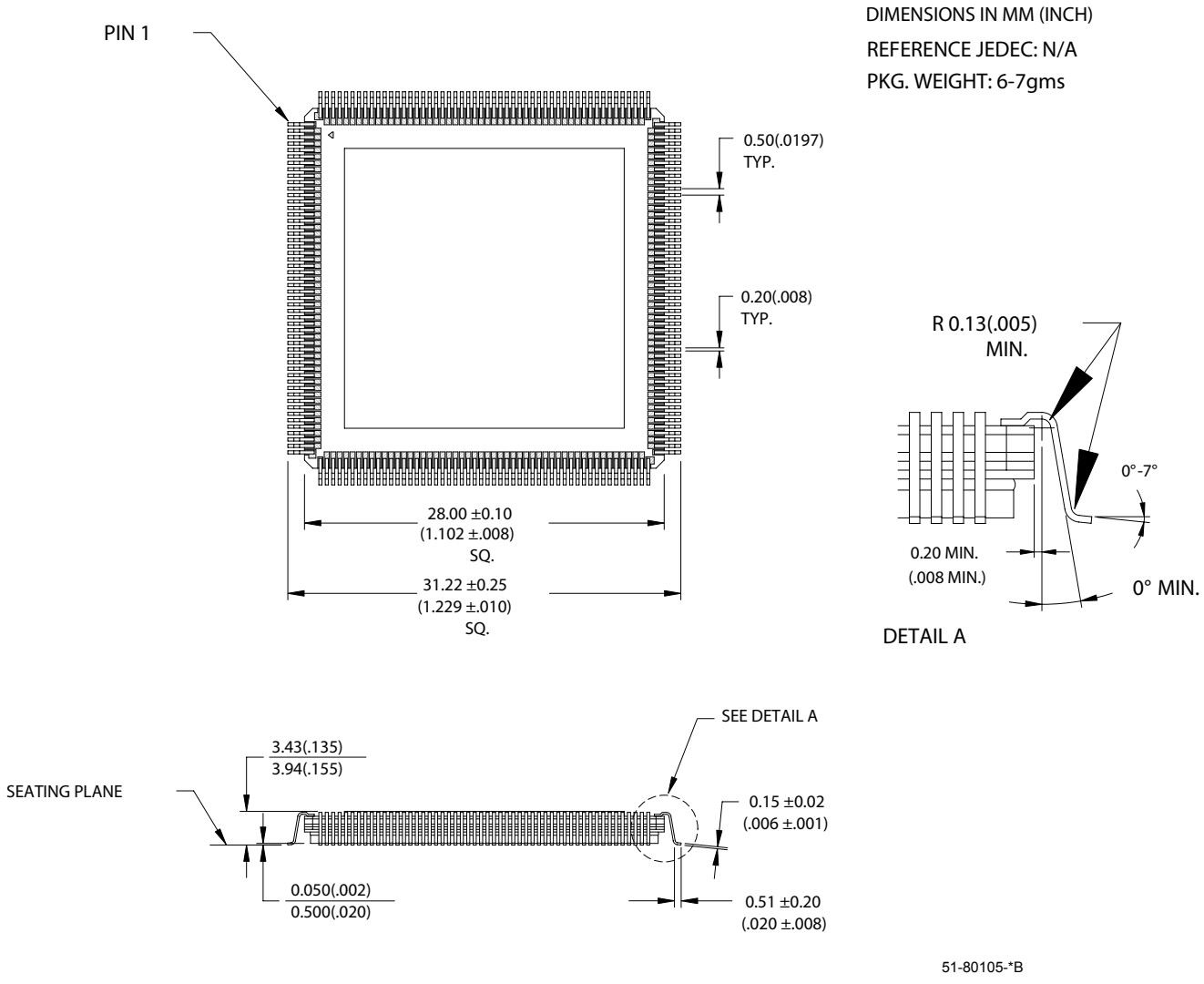
Package Diagrams (continued)

160-Lead Ceramic Quad Flatpack (Cavity Up) U162



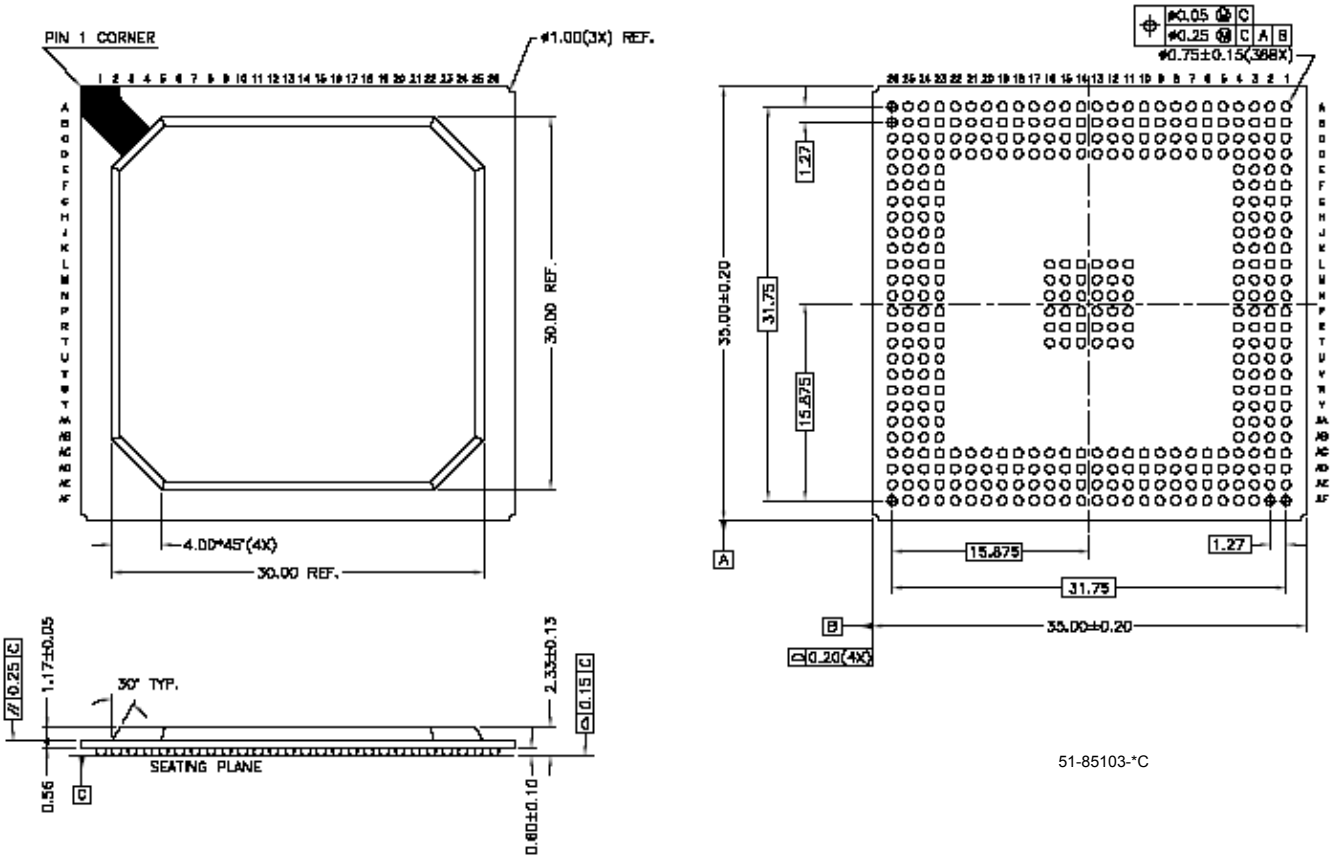
Package Diagrams (continued)

208-Lead Ceramic Quad Flatpack (Cavity Up) U208



Package Diagrams (continued)

388-Ball Plastic Ball Grid Array PBGA (35 x 35 x 2.33 mm) BG388



51-85103-*C